

IN THE CLAIMS

Please amend the claims as shown in the following detailed claim listing. The detailed claim listing is intended to reflect the amendment of previously pending claims 17, 21, 26, and 31. Claims 19 and 28 are canceled without prejudice.

The specific amendments to individual claims are detailed in the following detailed claim listing.

Claims 1-16 (Canceled)

17. (Currently amended) An electronic package substrate comprising:
a thin, flexible, electrically insulating film having a conductor region to mount an integrated circuit;
a plurality of traces within the film, including within the conductor region; ~~and~~
a plurality of lands on a surface of the film and coupled to the traces, wherein the lands are to mount corresponding pads of the integrated circuit in a ball grid array; and
wherein the film comprises a plurality of contiguous layers, selected ones of which comprise a plurality of traces.

18. (Original) The electronic package substrate recited in claim 17, wherein the film is formed of material from the group comprising a polymeric film, polyimide, polyester, polyparabanic acid, epoxy, and fiberglass.

Claims 19-20 (Canceled)

21. (Currently amended) An electronic package comprising:
a flexible, ~~an~~ electrically insulating film having a thickness in the range of approximately .15 to .90 millimeters, the film having a conductor region, a plurality of traces in the conductor region, and a plurality of lands formed directly upon a surface of the film and coupled to the traces; and

an integrated circuit having a plurality of pads coupled to the plurality of lands in a ball grid array.

22. (Original) The electronic package recited in claim 21, wherein the film is formed of material from the group comprising a polymeric film, polyimide, polyester, polyparabanic acid, epoxy, and fiberglass.

23. (Original) The electronic package recited in claim 21, wherein the film comprises a plurality of layers, each comprising a plurality of traces in the conductor region, and wherein each layer has a thickness within the range of approximately .15 to .30 millimeters.

Claims 24-25 (Canceled)

26. (Currently amended) An electronic system having at least one electronic assembly comprising:

a thin, flexible, electrically insulating film having a conductor region, a plurality of traces in the conductor region, and a plurality of lands formed directly upon a surface of the film and coupled to the traces; ~~and~~

an integrated circuit having a plurality of pads coupled to the plurality of lands in a ball grid array; and

wherein the film comprises a plurality of contiguous layers, selected ones of which comprise a plurality of traces in the conductor region.

27. (Original) The electronic system recited in claim 26, wherein the film is formed of material from the group comprising a polymeric film, polyimide, polyester, polyparabanic acid, epoxy, and fiberglass.

Claims 28-30 (Canceled)

31. (Currently amended) A data processing system comprising:
a bus coupling components in the data processing system;
a display coupled to the bus;
a memory coupled to the bus; and
a processor coupled to the bus and comprising an electronic assembly including,
a thin, flexible, electrically insulating film having a conductor region, a plurality of traces in the conductor region, and a plurality of lands formed directly upon a surface of the film and coupled to the traces; and
an integrated circuit having a plurality of pads coupled to the plurality of lands in a ball grid array.
32. (Original) The data processing system recited in claim 31, wherein the film is formed of material from the group comprising a polymeric film, polyimide, polyester, polyparabanic acid, epoxy, and fiberglass.
33. (Original) The data processing system recited in claim 31, wherein the film comprises a plurality of layers, each comprising a plurality of traces in the conductor region.
34. (Canceled)
35. (Previously added) The electronic package substrate recited in claim 17, wherein the film comprises one or more vias coupled to corresponding ones of the traces.
36. (Previously added) The electronic package substrate recited in claim 19, wherein the film comprises one or more vias to couple traces within different layers.

37. (Previously added) A package substrate comprising:
a thin, flexible, electrically insulating film having a conductor region to mount an integrated circuit;
a plurality of traces, at least some of which are within the conductor region;
one or more vias within the film and coupled to corresponding ones of the traces; and
a plurality of lands on a surface of the film and coupled to the traces, wherein the lands are to mount corresponding pads of the integrated circuit.
38. (Previously added) The package substrate recited in claim 37, wherein the film is formed of material from the group comprising a polymeric film, polyimide, polyester, polyparabanic acid, epoxy, and fiberglass.
39. (Previously added) The package substrate recited in claim 37, wherein the film comprises a plurality of layers, each comprising a plurality of traces.
40. (Previously added) The package substrate recited in claim 39, wherein the one or more vias couple traces within different layers.
41. (Previously added) The electronic package recited in claim 21, wherein the film comprises one or more vias coupled to corresponding ones of the traces.
42. (Previously added) The electronic package recited in claim 23, wherein the film comprises one or more vias to couple traces within different layers.
43. (Previously added) The electronic system recited in claim 26, wherein the film comprises one or more vias coupled to corresponding ones of the traces.
44. (Previously added) The electronic system recited in claim 28, wherein the film comprises one or more vias to couple traces within different layers.

AMENDMENT AND RESPONSE UNDER 37 CFR §1.116 – EXPEDITED PROCEDURE

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45. (Previously added) The data processing system recited in claim 31, wherein the film comprises one or more vias coupled to corresponding ones of the traces.

46. (Previously added) The data processing system recited in claim 33, wherein the film comprises one or more vias to couple traces within different layers.